



MOULD, ENCAPSULATING DEVICE AND METHOD OF ENCAPSULATION

ABSTRACT OF THE DISCLOSURE

The invention relates to a mould for encapsulating electronic components mounted on a carrier, comprising: at least two mould parts displaceable relative to each other, at least one of which is provided with a recess, and feed means for encapsulating material, wherein at least one of the mould parts is provided with a runner which connects on one side to a wall of a mould part co-defining a mould cavity and connects on the other side to a side of the mould part remote from the mould cavity. The invention also relates to an encapsulating device of which such a mould forms parts, and to a method for encapsulating electronic components mounted on a carrier.

5